Schottky Barrier Rectifier, Surface Mount

FSV340FP, FSV360FP

Features

- Low Forward Voltage Drop:
 - FSV340FP: 0.52 V Maximum at 3 A, $T_A = 25$ °C
 - FSV360FP: 0.65 V Maximum at 3 A, T_A = 25°C
- Larger Cathode Pad for Improved Power Dissipation
- Ultra Thin Profile Maximum Height of 1.0 mm
- High Surge Capacity
- UL Flammability 94V-0 Classification
- MSL 1
- Green Mold Compound
- These Devices are Pb–Free, Halogen Free Free and are RoHS Compliant

Specifications

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

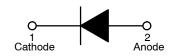
		Value		
Symbol	Parameter	FSV340FP	FSV360FP	Unit
V _{RRM}	Recurrent Peak Reverse Voltage	40	60	V
V _{RMS}	RMS Reverse Voltage	28	42	V
V_{R}	DC Blocking Voltage	40	60	V
I _{F(AV)}	Average Forward Current at $T_L = 75^{\circ}\text{C}$	3		Α
I _{FSM}	Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	80		A
T _J	Operating Junction Temperature Range	–55 to +150		°C
T _{STG}	Storage Temperature Range	-55 to +150		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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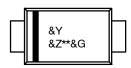
www.onsemi.com



Schottky Barrier Rectifier



MARKING DIAGRAM



Band Indicates Cathode

&Y = Binary Calendar Year Coding Scheme

&Z = Assembly Plant Code

** = Specific Device Code – (FC, FD)

&G = Single Digit Weekly Data Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet

FSV340FP, FSV360FP

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Note 1)

Symbol	Characteristic	Value	Unit
$\Psi_{\sf JL}$	Typical Thermal Characteristics, Junction-to-Lead (Note 2)	10	°C/W
$R_{ heta JA}$	Typical Thermal Resistance, Junction-to-Ambient	140	°C/W

^{1.} Per JESD51-3 recommended thermal test board. Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 3 A	FSV340FP	-	-	0.52	V
			FSV360FP	-	-	0.65	
I _R	Reverse Current	V _R = 40 V	FSV340FP	-	-	160	μΑ
		V _R = 60 V	FSV360FP	-	-	100	
T _{rr}	Reverse Recovery Time	I _F = 0.5 A, I _R = 1 A, I _{rr} = 0.25 A	FSV340FP	-	12.37	-	ns
		I _{rr} = 0.25 A	FSV360FP	-	10.62	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping [†]
FSV340FP	FC	SOD-123EP (Pb-Free/Halogen Free)	3000 / Tape & Reel
FSV360FP	FD	SOD-123EP (Pb-Free/Halogen Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{2.} Thermocouple soldered at cathode lead.

FSV340FP, FSV360FP

TYPICAL PERFORMANCE CHARACTERISTICS

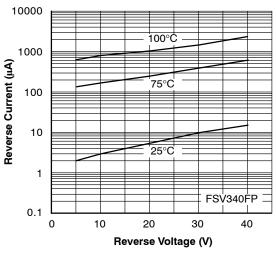


Figure 1. Typical Reverse Characteristics

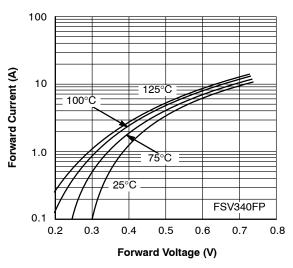


Figure 3. Typical Forward Characteristics

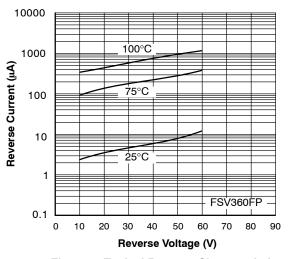


Figure 2. Typical Reverse Characteristics

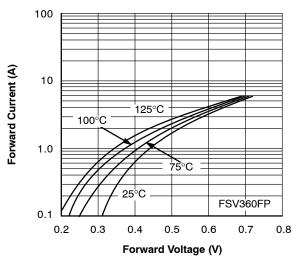


Figure 4. Typical Forward Characteristics

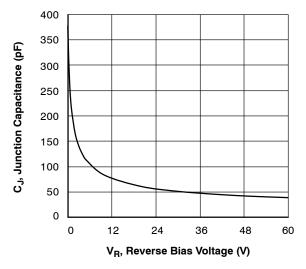
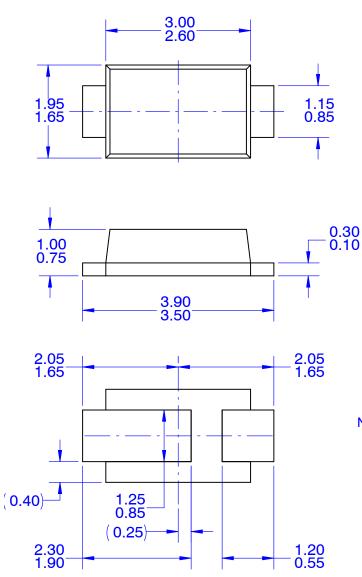


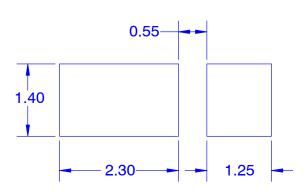
Figure 5. Typical Junction Capacitance



SOD-123EP CASE 425AC ISSUE O

DATE 31 AUG 2016





LAND PATTERN RECOMMENDATION LONG PAD IS CATHODE

NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS,
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